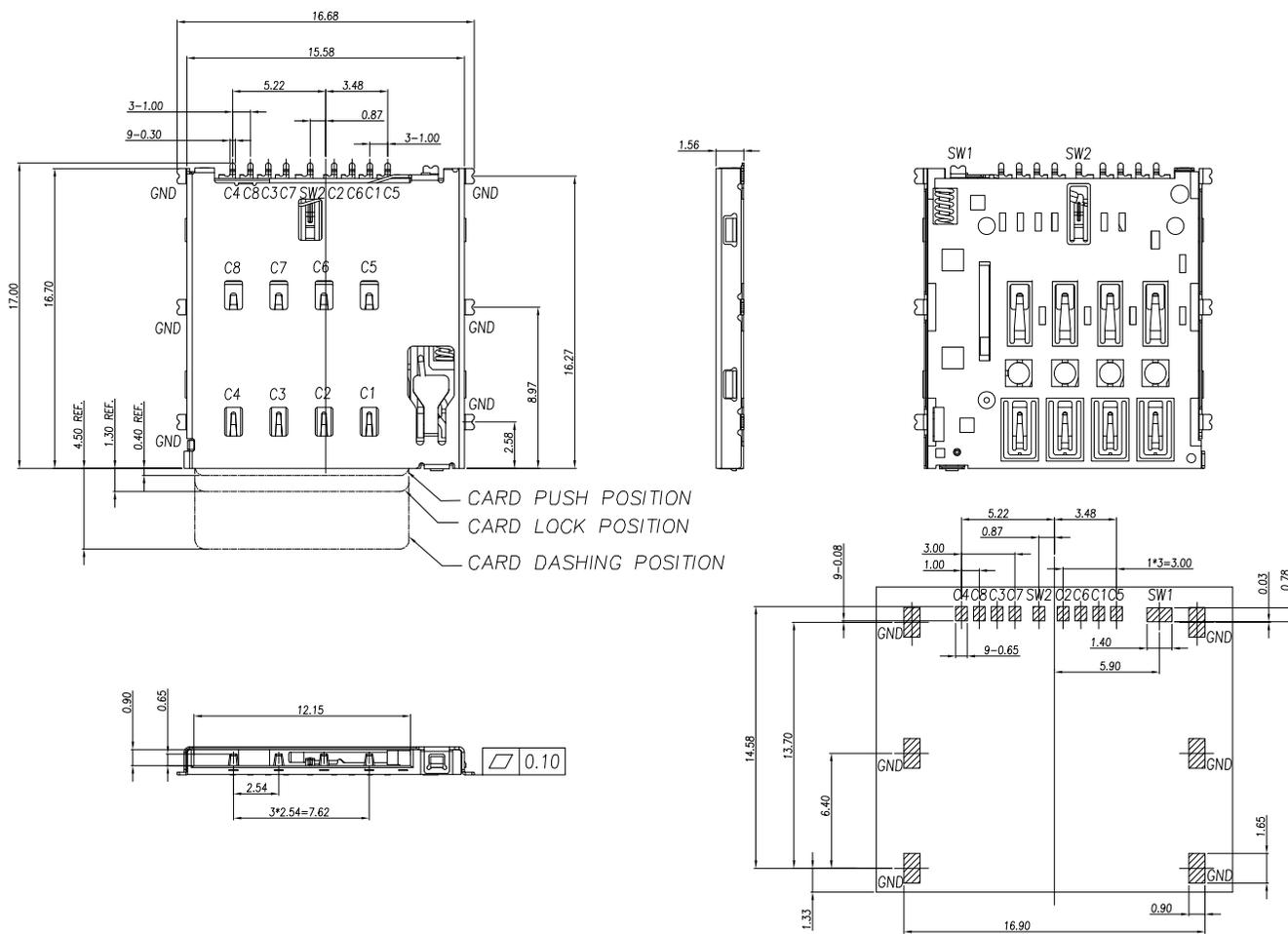


# GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2021/04/21	Hanson



- NOTES:
- MATERIAL:
    - Housing: High Temperature Thermoplastic UL94V-0; Color Black.
    - Terminal: Copper Alloy.
    - Shell: Stainless Steel.
  - SPECIALITY:
    - Rated current: 0.5A
    - Rated voltage: 30V
    - Contact Resistance: 100mΩ MAX
    - Insulation Resistance: 1000MΩ MIN 500V DC
    - Dielectric withstanding voltage: 500V AC.
    - Solder ability: 255±5°C, 5±0.5s.
    - Durability: 3000 Cycles Min.
    - Operating condition: Temperature -40°C ~ +75°C; Humidity 80% R.H MAX

MATRIX PART NO:  
 MSM-01-01-10-15-91  
 Matrix Micro SIM  
 01 : Push  
 02 : Non-Push  
 Plating  
 01:G/F  
 05:5u  
 30:30u  
 Series Number  
 Height  
 Pin number  
 10:10pin

### DETECT SWITCH

CARD INSERTING POSITION	CLOSE	CLOSE	SW1	SW2
NO CARD	OPEN	OPEN	SW1	SW2

Card is not inserted;  
 Sw2 and Sw1/GND pin is open  
 Card is inserted;  
 Sw2 and Sw1/GND pin is close

RECOMMENDED P.C.B LAYOUT  
 TOP VIEW(TOLERANCE±0.05)  
 PAD AREA

6	Housing	1PC	LCP UL94V-0	BLACK
5	LINK	1PC	SUS304	
4	SPRING	1PC	SWP-B	plating Ni: 30u"min
3	Slider	1PC	LCP UL94V-0	BLACK
2	COVER	1PC	SUS304	Solder plating Gold 1u" , Ni 30u"min
1	Terminal	1PC	C5210-EH,T=0.10	plating Gold 1u" , Ni 50u"min
NO	Description	Dosage	Material	Color/plating



## Matrix Electronics Co.,Ltd

TOLERANCE: X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 ANGLE: ±3°	DESIGN BY : Hanson Huang	DATE : 2021/04/21	PART NAME: Micro SIM card 1.56H
APPROVED BY1: Richard Hsieh	DATE : 2021/04/21	PART NO. MSM-01-01-10-15-91	MOLD NO. NA
APPROVED BY2: Richard Hsieh	DATE : 2021/04/21	DRAW NO.	SHEET NO. 1 OF 1